# RESISTOR

## THIN FILM CHIP RESISTOR

# 0.007 Sq.

Minimum bonding area for  $< 100\Omega$  Resistance.

### **MSMR1 SERIES**

#### **MECHANICAL DATA**

SIZE SUBSTRATE RESISTOR BONDING PADS

**BACKSIDE SURFACE** 

0.012" x 0.009" x 0.010" (±0.003")
SILICON, ALUMINA, QUARTZ, OR GLASS
NICHROME OR TANTALUM NITRIDE
15,000 Å MINIMUM GOLD
10,000 Å MINIMUM: ALUMINUM OPTIONAL
BARE SUBSTRATE

#### **ELECTRICAL DATA**

RESISTANCE RANGE SILICON, QUARTZ, GLASS ALUMINA TOLERANCES NICHROME  $2\Omega \ \ TO \ \ 700 K \Omega*$   $2\Omega \ \ TO \ \ 33 K \Omega$   $0.01\% \ \ TO \ \ 10\%$  (Value Dependent)

**GOLD BACK OPTIONAL** 

TANTALUM NITRIDE  $2\Omega$  TO 700K  $\Omega\star$   $2\Omega$  TO 33K  $\Omega$  0.01% TO 10% (Value Dependent)

T.C.R.

±25ppm/°C STANDARD OPTIONAL TO ±5ppm/°C

±150ppm/°C STANDARD
OPTIONAL TO ±10ppm/°C (S, Q, G)

±25ppm/°C (A)

#### **SERIES DATA**

**CURRENT NOISE** 

DIELECTRIC BREAKDOWN
INSULATION RESISTANCE
OPERATING VOLTAGE
POWER RATING
SHORT TERM OVERLOAD
HIGH TEMP EXPOSURE
THERMAL SHOCK
MOISTURE RESISTANCE
STABILITY

OPERATING TEMP RANGE STRAY DISTRIBUTED CAPACITANCE SILICON  $\leq$  100  $\Omega_{\rm t} \gtrsim 250 {\rm K}\Omega$ : -30 dB 400 V MIN.\* 1012  $\Omega$  MIN. 100 V MAX. 50 mW (70°C DERATED LIN

101Ω TO TO 250KΩ: -40dB

50 mW (70°C DERATED LINEARLY TO 150°C)  $P = \sqrt{(E*R)}$  5X RATED POWER, 25°C, 5 SEC.,  $\pm$ 0.25% MAX.  $\Delta$ R/R: 0.1% MSI TYPICAL 150°C, 100 HRS.,  $\pm$ 0.25% MAX.  $\Delta$ R/R: 0.03% MSI TYPICAL MIL-STD 202, METHOD 107F,  $\pm$ 0.25% MAX.  $\Delta$ R/R: 0.1% MSI TYPICAL MIL-STD 202, METHOD 106,  $\pm$ 0.5% MAX.  $\Delta$ R/R: 0.1% MSI TYPICAL 1000 HRS., 70°C, 125mW,  $\pm$ 0.5% MAX.  $\Delta$ R/R: 0.1% MSI TYPICAL

-55°C TO +125°C

 SILICON
 2pF

 ALUMINA
 0.06pF

 QUARTZ
 0.02pF

#### PART NUMBER DESIGNATION

MSMR1	X	X	_	XXXXX	X	_	<u> </u>
SERIES	SUBSTRATE	RESISTIVE FILM		OHMIC VALUE 5-Digit	TOLERANCE S = 0.01%*		OPTION DESIGNATOR
	A = Alumina G = Glass Q = Quartz S = Silicon	N = Nichrome T = Tantalum Nitride		Number: 1st 4 Digits Are Significant With "R" As Decimal Point When Required. 5th Digit Represents Number of Zeros.	Q = 0.05%* B = 0.1% D = 0.5% F = 1% G = 2% J = 5% K = 10%	B C D E GB F	(If Required) A = ±50ppm/°C B = ±25ppm/°C C = ±10ppm/°C D = ±5ppm/°C E = Aluminum Bond Pads B = Gold Backside F = ±100ppm/°C G = Gold Pads (always used when no other option is required)



20 DAVID ROAD, N. ATTLEBORO, MA 02760 508-695-0203 FAX: 508-695-6076 EXAMPLE: MSTF 1SN-50R00F-BGB = 0.015" x 0.015", Silicon Substrate, Nichrome Resistor,  $50\Omega$ ,  $\pm 1\%$  Tol.,  $\pm 25$ ppm/°C, Gold Backside.